



# Flip Chip Bumping Factory Qualification at SPIL for Defense-grade 7 Series XQ FPGA Products

XCN16003 (v1.0) June 27, 2016

Product Change Notice - For Information Only

## Overview

The purpose of this notification is to communicate that Xilinx has qualified SPIL Bumping for 7 Series FPGAs Defense-grade “XQ” flip chip products.

## Description

This notification is to inform customers that 7- Series FPGAs Defense-grade “XQ” flip chip product bumping will be performed at Siliconware Precision Industry Ltd. (SPIL). SPIL has been a Xilinx qualified flip chip bumping and assembly supplier for all XQ and flip chip products, which include Virtex®-II Pro, Virtex-4, Virtex-5 and Virtex-6. All bill of materials, dimensions and major process steps remain unchanged. There is no change to the form, fit, or function.

## Products Affected

This change affects all 7 Series FPGAs “XQ” products.

Table 1: 7 Series FPGAs XQ Products Family Affected

Part Number	Part Number	Part Number
XQ7A200T-1RB484I	XQ7K410T-L2RF900E	XQ7VX690T-2RF1761I
XQ7A200T-1RB484M	XQ7K410T-L2RF900I	XQ7VX690T-2RF1930I
XQ7A200T-1RB676I	XQ7V585T-1RF1157I	XQ7VX980T-1RF1930I
XQ7A200T-1RB676M	XQ7V585T-1RF1157M	XQ7VX980T-L2RF1930E
XQ7A200T-1RS484I	XQ7V585T-1RF1761I	XQ7Z030-1RB484I
XQ7A200T-1RS484M	XQ7V585T-1RF1761M	XQ7Z030-1RB484Q
XQ7A200T-2RB484I	XQ7V585T-2RF1157I	XQ7Z030-1RF676I
XQ7A200T-2RB676I	XQ7V585T-2RF1761I	XQ7Z030-1RF676Q
XQ7A200T-2RS484I	XQ7V585T-L2RF1157E	XQ7Z030-2RB484I
XQ7A200T-L1RB484I	XQ7V585T-L2RF1761E	XQ7Z030-2RF676I
XQ7A200T-L1RB676I	XQ7VX330T-1RF1157I	XQ7Z030-L2RB484I
XQ7A200T-L1RS484I	XQ7VX330T-1RF1157M	XQ7Z030-L2RF676I
XQ7K325T-1RF676I	XQ7VX330T-1RF1761I	XQ7Z045-1RF676I
XQ7K325T-1RF676M	XQ7VX330T-1RF1761M	XQ7Z045-1RF676Q
XQ7K325T-1RF900I	XQ7VX330T-2RF1157I	XQ7Z045-1RF900I
XQ7K325T-1RF900M	XQ7VX330T-2RF1761I	XQ7K325T-2RF676I

Table 1 (continued): 7 Series FPGAs XQ Products Family Affected

Part Number	Part Number	Part Number
XQ7K325T-2RF900I	XQ7VX485T-1RF1761I	XQ7Z045-2RF676I
XQ7K325T-L1RF676M	XQ7VX485T-1RF1761M	XQ7Z045-2RF900I
XQ7K325T-L2RF676E	XQ7VX485T-1RF1930I	XQ7Z045-L1RF676Q
XQ7K325T-L2RF676I	XQ7VX485T-1RF1930M	XQ7Z045-L1RFG676Q
XQ7K325T-L2RF900E	XQ7VX485T-2RF1761I	XQ7Z045-L2RF676I
XQ7K325T-L2RF900I	XQ7VX485T-2RF1930I	XQ7Z045-L2RF900I
XQ7K410T-1RF676I	XQ7VX485T-L2RF1761E	XQ7Z100-1RF1156I
XQ7K410T-1RF676M	XQ7VX485T-L2RF1930E	XQ7Z100-1RF900I
XQ7K410T-1RF900I	XQ7VX690T-1RF1157I	XQ7Z100-2RF1156I
XQ7K410T-1RF900M	XQ7VX690T-1RF1158I	XQ7Z100-2RF900I
XQ7K410T-2RF676I	XQ7VX690T-1RF1761I	XQ7Z100-L2RF1156I
XQ7K410T-2RF900I	XQ7VX690T-1RF1930I	XQ7Z100-L2RF900I
XQ7K410T-L2RF676E	XQ7VX690T-2RF1157I	
XQ7K410T-L2RF676I	XQ7VX690T-2RF1158I	
XQ7VX330T-L2RF1157E	XQ7Z045-1RF900Q	
XQ7VX330T-L2RF1761E	XQ7Z045-1RFG676Q	

## Key Dates and Ordering Information

Xilinx will begin cut-over to SPIL bump factory on date code 1625.

## Qualification Data

Qualification was completed successfully. Data can be provided upon request.

## Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

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## Revision History

The following table shows the revision history for this document:

Date	Version	Description of Revisions
06/27/2016	1.0	Initial release.

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